

100V N-Channel MOSFETs

General Description

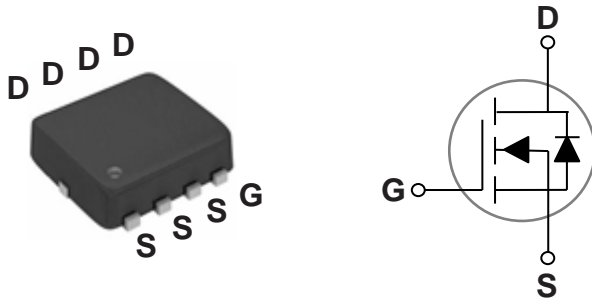
These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R _{DS(ON)}	I _D
100V	11.8mΩ	48A

Features

- 100V,48A, R_{DS(ON)} = 11.8mΩ @V_{GS} = 10V
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

PPAK3X3 Pin Configuration



Applications

- Networking
- Load Switch
- LED applications

Absolute Maximum Ratings T_c=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D	Drain Current – Continuous (T _C =25°C)	48	A
	Drain Current – Continuous (T _C =100°C)	30	A
I _{DM}	Drain Current – Pulsed ¹	192	A
EAS	Single Pulse Avalanche Energy ²	115	mJ
IAS	Single Pulse Avalanche Current ²	48	A
P _D	Power Dissipation (T _C =25°C)	61	W
	Power Dissipation – Derate above 25°C	0.49	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	62	°C/W
R _{θJC}	Thermal Resistance Junction to Case	---	2.04	°C/W



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Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	---	---	V
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	1	μA
		$V_{DS}=80V, V_{GS}=0V, T_J=85\text{ }^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V, I_D=20A$	---	9.8	11.8	m Ω
		$V_{GS}=4.5V, I_D=15A$	---	13	16.8	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2	1.6	2.5	V
gfs	Forward Transconductance	$V_{DS}=10V, I_D=3A$	---	10	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{3, 4}	$V_{DS}=50V, V_{GS}=10V, I_D=10A$	---	26.1	39	nC
Q_{gs}	Gate-Source Charge ^{3, 4}		---	6.5	10	
Q_{gd}	Gate-Drain Charge ^{3, 4}		---	5.3	8	
$T_{d(on)}$	Turn-On Delay Time ^{3, 4}	$V_{DD}=50V, V_{GS}=10V, R_G=6\Omega, I_D=10A$	---	14.2	28	ns
T_r	Rise Time ^{3, 4}		---	20.8	42	
$T_{d(off)}$	Turn-Off Delay Time ^{3, 4}		---	42	84	
T_f	Fall Time ^{3, 4}		---	30	60	
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V, F=1MHz$	---	1450	2145	pF
C_{oss}	Output Capacitance		---	215	322	
C_{rss}	Reverse Transfer Capacitance		---	8	20	
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	1.04	---	Ω

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V, \text{Force Current}$	---	---	48	A
I_{SM}	Pulsed Source Current		---	---	96	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$	---	---	1	V
t_{rr}	Reverse Recovery Time	$V_R=100V, I_S=10A$	---	155	---	ns
Q_{rr}	Reverse Recovery Charge		$dI/dt=100A/\mu s, T_J=25\text{ }^\circ\text{C}$	---	230	---

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. $V_{DD}=50V, V_{GS}=10V, L=0.1mH, I_{AS}=48A, R_G=25\Omega, \text{Starting } T_J=25\text{ }^\circ\text{C}$.
3. The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
4. Essentially independent of operating temperature.



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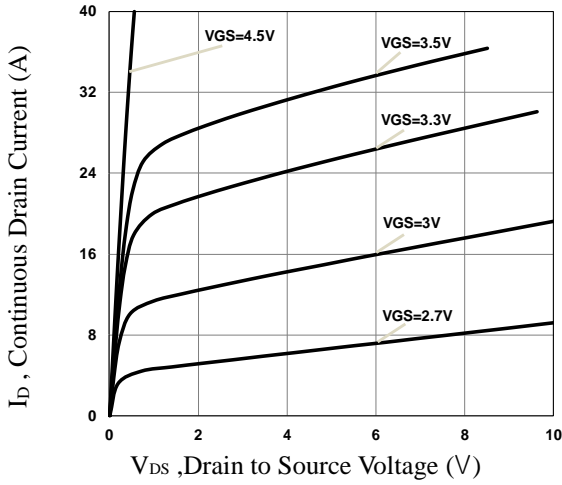


Fig.1 Typical Output Characteristics

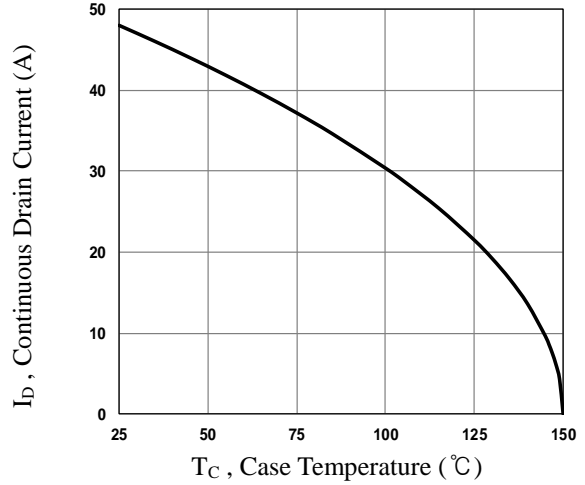


Fig.2 Continuous Drain Current vs. T_C

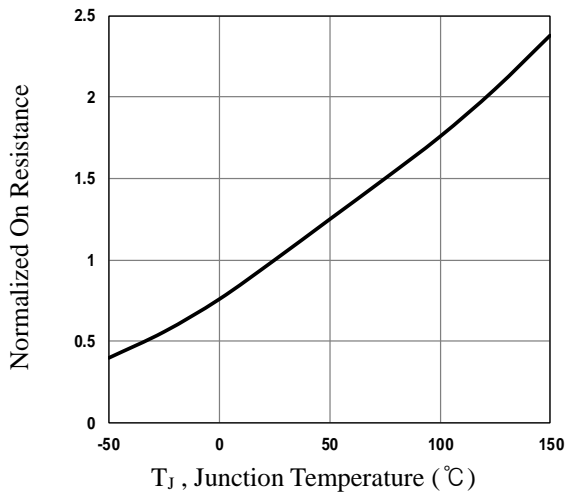


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

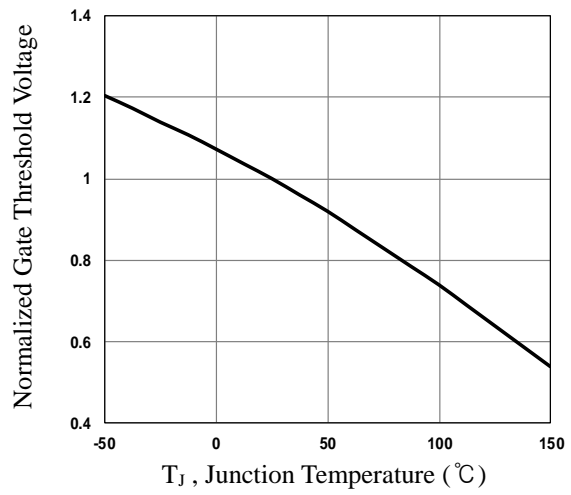


Fig.4 Normalized V_{th} vs. T_J

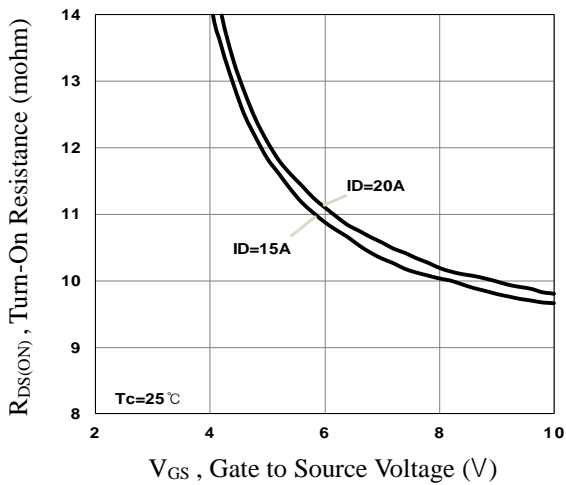


Fig.5 Turn-On Resistance vs. V_{GS}

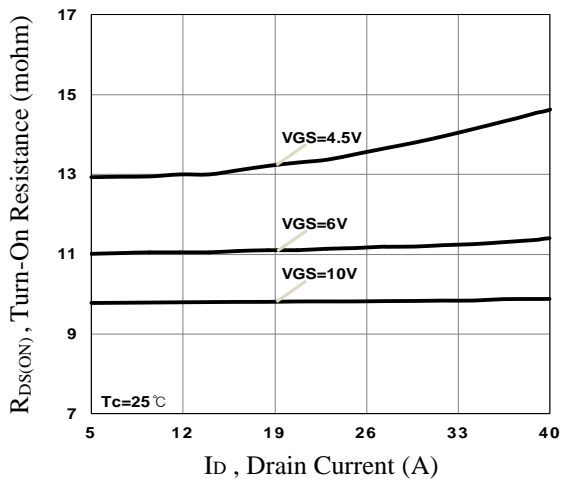


Fig.6 Turn-On Resistance vs. I_D

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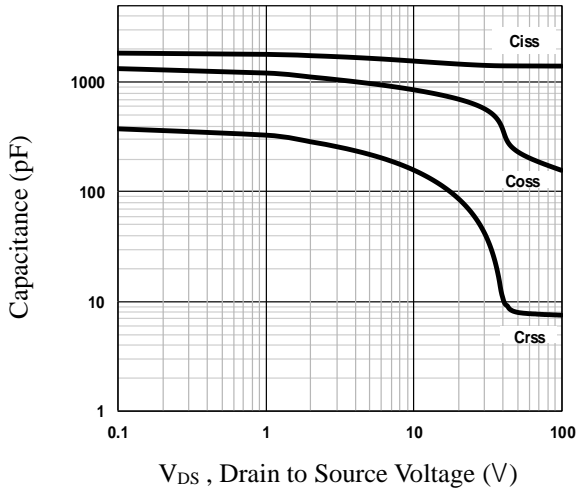


Fig.7 Capacitance Characteristics

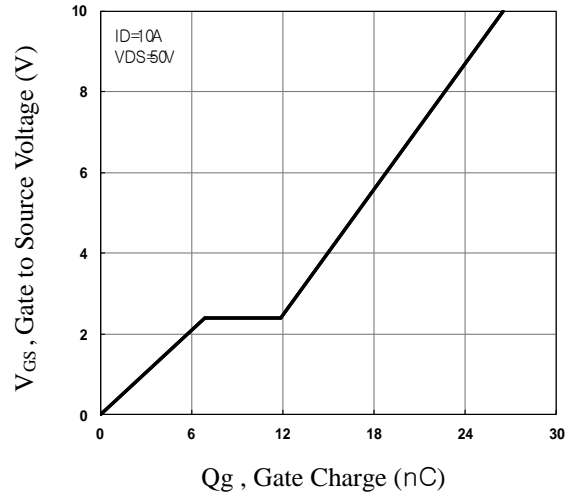


Fig.8 Gate Charge Characteristics

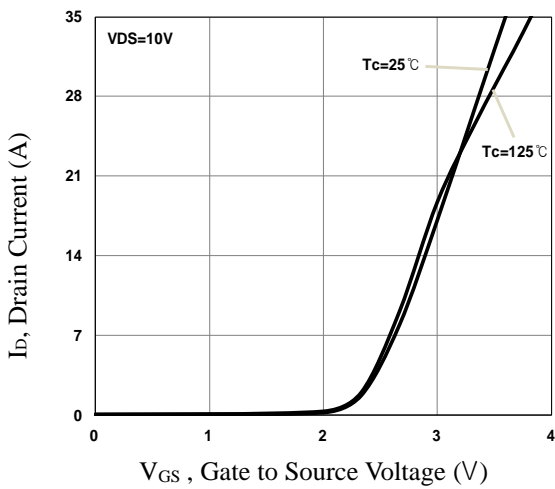


Fig.9 Transfer Characteristics

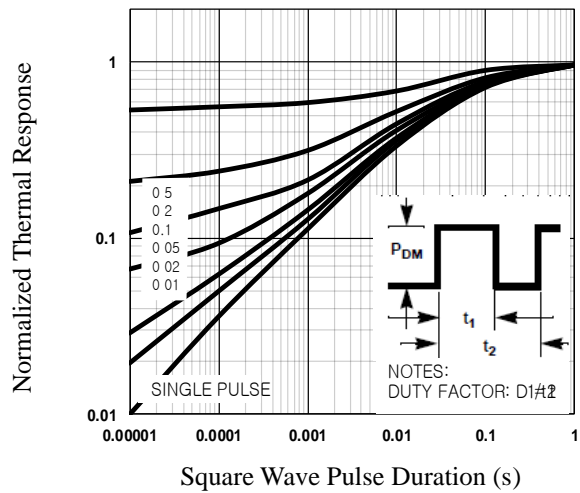


Fig.10 Normalized Transient Impedance

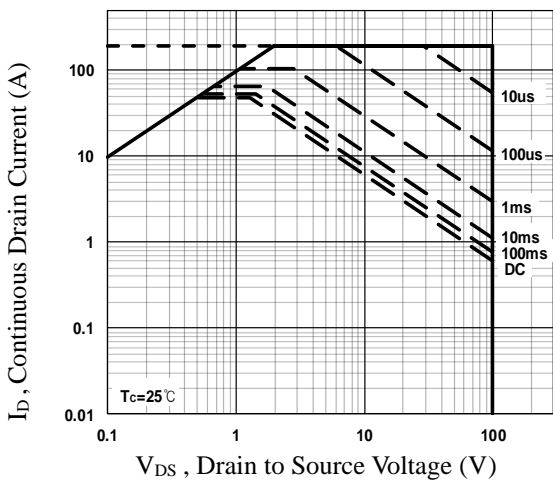


Fig.11 Maximum Safe Operation Area

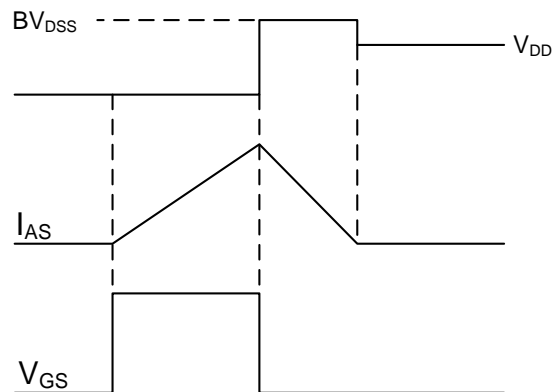
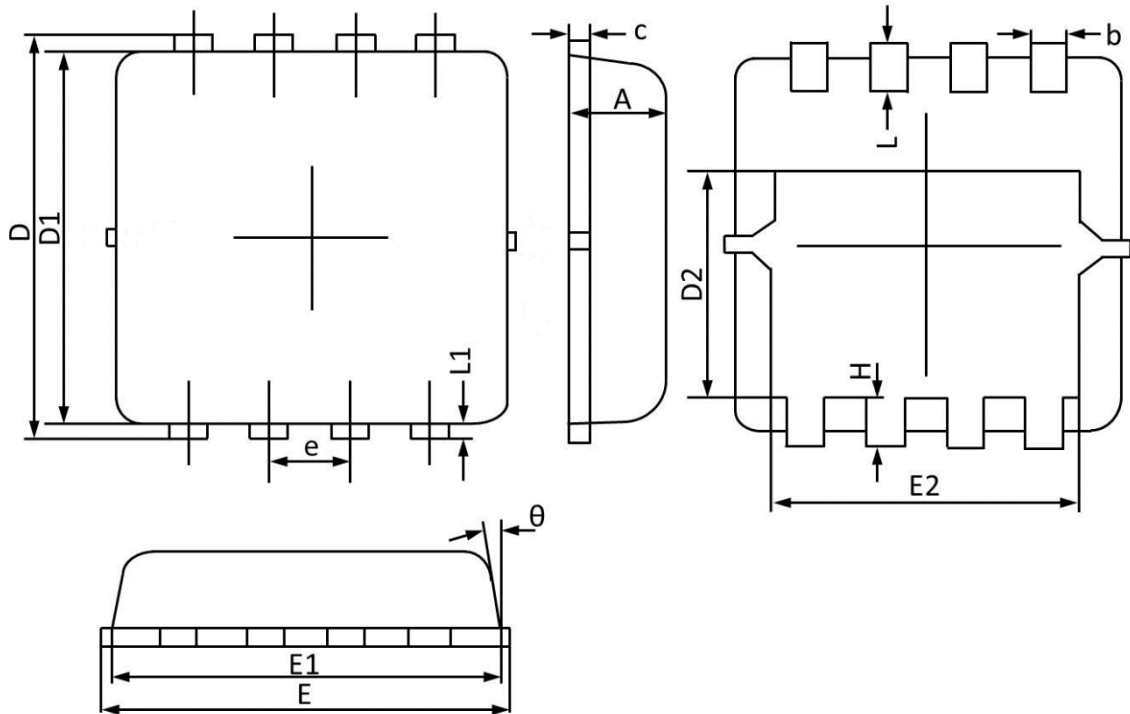


Fig.12 EAS Waveform

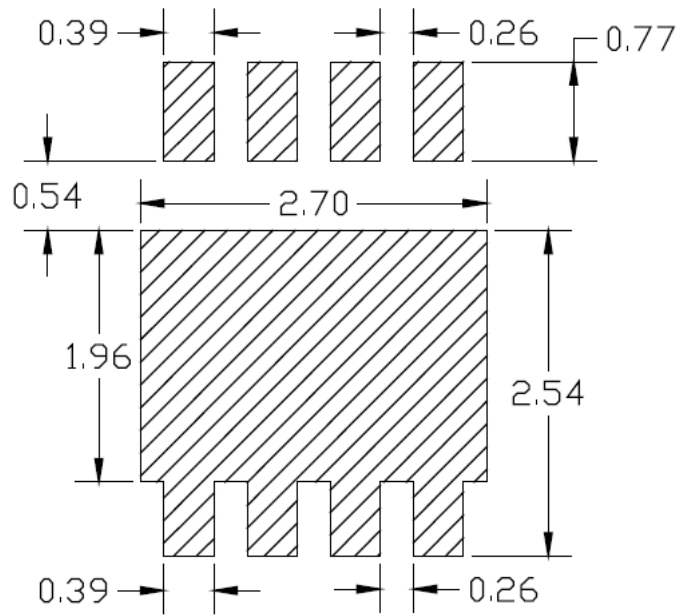
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PPAK3x3 PACKAGE INFORMATION


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
b	0.350	0.250	0.014	0.010
c	0.250	0.100	0.010	0.004
D	3.500	3.050	0.138	0.120
D1	3.200	2.900	0.126	0.114
D2	1.950	1.350	0.077	0.053
E	3.400	3.000	0.134	0.118
E1	3.300	2.900	0.130	0.114
E2	2.600	2.350	0.102	0.093
e	0.65BSC		0.026BSC	
H	0.750	0.300	0.030	0.012
L	0.600	0.300	0.024	0.012
L1	0.200	0.060	0.008	0.002
θ	14°	6°	14°	6°



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PPAK3X3 RECOMMENDED LAND PATTERN



unit : mm